glycol monomethyl ether and 29.1 g of propylene glycol monomethyl ether acetate was spin-coated at a thickness of 0.1 mm onto a 300-mm silicon wafer (thickness: 775 μm) and then cured at 200°C for 1 minute to form a separating agent layer. On the 300-mm silicon wafer having the separating agent layer formed thereon, a film of an adhesive was formed by spin coating to give a thickness of about 50 μm. The adhesive film was heated at 110°C for 1 minute to remove the solvent.

The silicon wafer having the adhesive layer was attached to a 300-mm glass wafer so that the adhesive layer was disposed therebetween, using XBS (attachment device manufactured by SUSS MicroTec AG). Thus, a layered body was produced.

Here, a layered body in which the attachment was achieved without voids was evaluated as (○), and a layered body in which the attachment was not achieved with the formation of voids was evaluated as (×).